

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

1. (Original) A module comprising:

a first electronic component including first and second electrodes;

a board including third and fourth electrodes on a first surface thereof, the third and fourth electrodes being coupled to the first and second electrodes of the first electronic component, respectively;

first and second solders for connecting the first and second electrodes of the first electronic component to the third and fourth electrodes of the board, respectively;

a first insulating resin for covering the first electronic component, the first surface of the board, the first and second solders, and the first to fourth electrodes;

a first solder resist provided on the first surface of the board and around the third electrode; and

a second solder resist provided on the first surface of the board and around the fourth electrode, the second solder resist being separated from the first solder resist at a portion between the first electronic component and the board.

2. (Original) The module as defined in claim 1, wherein the first and second solder resists are provided only around the third and fourth electrodes, respectively.

3. (Original) The module as defined in claim 1, wherein the first insulating resin includes

thermosetting resin, and

inorganic filler by a rate ranging from 50wt.% to 95wt.% having a particle diameter less than a clearance between the board and the first electronic component.

4. (Original) The module as defined in claim 1, wherein the first insulating resin includes

a second insulating resin provided among the first electronic component, the board, and the first and second solders, and

a third insulating resin made of material different from material of the second insulating resin, the first electronic component being located between the third insulating resin and the board.

5. (Original) The module as defined in claim 4, wherein the second insulating resin includes

thermosetting resin, and

inorganic filler by a rate ranging from 10wt.% to 70wt.% having a particle diameter less than a clearance between the board and the first electronic component.

6. (Original) The module as defined in claim 4, wherein the second insulating resin has a bending modulus less than 20GPa.

7. (Original) The module as defined in claim 4, further comprising a metal film for covering a whole surface of the third insulating resin.

8. (Original) The module as defined in claim 1, wherein the first insulating resin has a bending modulus less than 20GPa.

9. (Original) The module as defined in claim 1, further comprising:

a second electronic component including fifth and sixth electrodes;

seventh and eighth electrodes coupled to the fifth and sixth electrodes of the second electronic component, respectively, and provided on the first surface of the board;

third and fourth solders for connecting the fifth and sixth electrodes of the second electronic component to the seventh and eighth electrodes of the board, respectively; and

a second insulating resin provided between the second electronic component and the board,

wherein the first resin covers the first and second electronic components, the first surface of the board, the first to fourth solders, and the first to eighth electrodes.

10. (Original) The module as defined in claim 9, wherein the first resin includes

a second insulating resin provided between the second component and the board and covering the third and fourth solders, and

a third insulating made of material different from material of the second insulating resin and covering the second insulating resin, the first and second electronic components being located between the third insulating resin and the board.

11. (Original) The module as defined in claim 10, further comprising a wall of solder resist on the first surface of the board at an interface between the second insulating resin and the third insulating resin.

12. (Original) The module as defined in claim 10, further comprising third and fourth solder resists provided on the first surface of the board and around the seventh and eighth electrodes, respectively.

13. (Original) The module as defined in claim 12, wherein the third and fourth solder resists are separated from each other at a portion between the second electronic component and the board.

14. (Original) The module as defined in claim 12, wherein the third and fourth solder resists are connected at a portion between the second electronic component and the board.

15. (Original) The module as defined in claim 10, wherein the second insulating resin has a thermal expansion coefficient larger than a thermal expansion coefficient of the third insulating resin.

16. (Original) The module as defined in claim 9, wherein a distance between the seventh electrode and the eighth electrode is not more than a distance between the fifth electrode and the sixth electrode.

17. (Original) The module as defined in claim 1, wherein a distance between the third electrode and the fourth electrode is not more than a distance between the first electrode and the second electrode.

18. (Original) The module as defined in claim 1, further comprising a metal film for covering a whole surface of the first insulating resin.

19. (Currently Amended) A module comprising:

an electronic component including first and second electrodes;

a board including third and fourth electrodes on a first surface thereof, the third and fourth electrodes are coupled to the first and second electrodes of the electronic component, respectively, wherein a distance between the third electrode and the fourth electrode is not more than a distance between the first electrode and the second electrode;

first and second solders for connecting the first and second electrodes of the electronic component to the third and the fourth electrodes, respectively; and

an insulating resin for covering the electronic component, the first surface of the board, and the first and second solders;

a first solder resist provided on the first surface of the board and around the third electrode; and

a second solder resist provided on the first surface of the board and around the fourth electrode, the second solder resist being separated from the first solder resist at a portion between the electronic component and the board.

20. (Original) The module as defined in claim 19, wherein the first and the second solders have first and second contours located between the electronic component and the board, respectively, and the first and second contours extend in directions approaching each other as the first and second contours approach the wiring board from the electronic component.

21. (Cancelled).

22. (Currently Amended) The module as defined in ~~claim 21~~claim 19, wherein the first and second solder resists are provided only around the third and fourth electrodes, respectively.

23. (Original) The module as defined in claim 19, further comprising a fifth electrode electrically connected to the third electrode and provided on a second surface of the board.

24. (Original) The module as defined in claim 19, further comprising a metal film for covering a whole surface of the insulating resin.